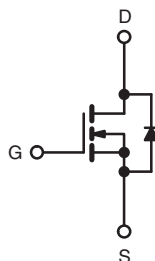
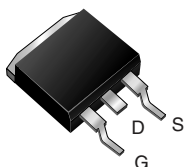


## Power MOSFET

### PRODUCT SUMMARY

|                           |                        |      |
|---------------------------|------------------------|------|
| $V_{DS}$ (V)              | 200                    |      |
| $R_{DS(on)}$ ( $\Omega$ ) | $V_{GS} = 10\text{ V}$ | 0.40 |
| $Q_g$ (Max.) (nC)         | 43                     |      |
| $Q_{gs}$ (nC)             | 7.0                    |      |
| $Q_{gd}$ (nC)             | 23                     |      |
| Configuration             | Single                 |      |

**D<sup>2</sup>PAK (TO-263)**


N-Channel MOSFET

### FEATURES

- Halogen-free According to IEC 61249-2-21 Definition
- Surface Mount
- Available in Tape and Reel
- Dynamic  $dV/dt$  Rating
- Repetitive Avalanche Rated
- Fast Switching
- Ease of Paralleling
- Simple Drive Requirements
- Compliant to RoHS Directive 2002/95/EC



**RoHS\***  
COMPLIANT  
HALOGEN  
**FREE**  
Available

### DESCRIPTION

Third generation Power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The D<sup>2</sup>PAK is a surface mount power package capable of accommodating die sizes up to HEX-4. It provides the highest power capability and the lowest possible on-resistance in any existing surface mount package. The D<sup>2</sup>PAK is suitable for high current applications because of its low internal connection resistance and can dissipate up to 2.0 W in a typical surface mount application.

### ORDERING INFORMATION

| Package                         | D <sup>2</sup> PAK (TO-263) | D <sup>2</sup> PAK (TO-263)   | D <sup>2</sup> PAK (TO-263)  |
|---------------------------------|-----------------------------|-------------------------------|------------------------------|
| Lead (Pb)-free and Halogen-free | SiHF630S-GE3                | SiHF630STR-L-GE3 <sup>a</sup> | SiHF630STRR-GE3 <sup>a</sup> |
| Lead (Pb)-free                  | IRF630SPbF                  | IRF630STRLPbF <sup>a</sup>    | IRF630STRRPbF <sup>a</sup>   |
|                                 | SiHF630S-E3                 | SiHF630STL-E3 <sup>a</sup>    | SiHF630STR-E3 <sup>a</sup>   |

#### Note

a. See device orientation.

### ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^\circ\text{C}$ , unless otherwise noted)

| PARAMETER                                          |                         |                         | SYMBOL          | LIMIT | UNIT |
|----------------------------------------------------|-------------------------|-------------------------|-----------------|-------|------|
| Drain-Source Voltage                               |                         |                         | V <sub>DS</sub> | 200   | V    |
| Gate-Source Voltage                                |                         |                         | V <sub>GS</sub> | ± 20  |      |
| Continuous Drain Current                           | V <sub>GS</sub> at 10 V | T <sub>C</sub> = 25 °C  | I <sub>D</sub>  | 9.0   | A    |
|                                                    |                         | T <sub>C</sub> = 100 °C |                 | 5.7   |      |
| Pulsed Drain Current <sup>a</sup>                  |                         |                         | I <sub>DM</sub> | 36    | W/°C |
| Linear Derating Factor                             |                         |                         |                 | 0.59  |      |
| Linear Derating Factor (PCB Mount) <sup>e</sup>    |                         |                         |                 | 0.025 |      |
| Single Pulse Avalanche Energy <sup>b</sup>         |                         |                         | E <sub>AS</sub> | 250   | mJ   |
| Repetitive Avalanche Current <sup>a</sup>          |                         |                         | I <sub>AR</sub> | 9.0   | A    |
| Repetitive Avalanche Energy <sup>a</sup>           |                         |                         | E <sub>AR</sub> | 7.4   | mJ   |
| Maximum Power Dissipation                          | T <sub>C</sub> = 25 °C  |                         | P <sub>D</sub>  | 74    | W    |
| Maximum Power Dissipation (PCB Mount) <sup>e</sup> | T <sub>A</sub> = 25 °C  |                         |                 | 3.0   |      |

\* Pb containing terminations are not RoHS compliant, exemptions may apply

|                               |         |     |      |
|-------------------------------|---------|-----|------|
| Peak Diode Recovery $dV/dt^c$ | $dV/dt$ | 5.0 | V/ns |
|-------------------------------|---------|-----|------|

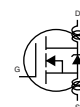
| ABSOLUTE MAXIMUM RATINGS ( $T_C = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted) |                |                  |                    |
|-----------------------------------------------------------------------------------------|----------------|------------------|--------------------|
| PARAMETER                                                                               | SYMBOL         | LIMIT            | UNIT               |
| Operating Junction and Storage Temperature Range                                        | $T_J, T_{stg}$ | - 55 to + 150    | $^{\circ}\text{C}$ |
| Soldering Recommendations (Peak Temperature)                                            | for 10 s       | 300 <sup>d</sup> |                    |

## Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- $V_{DD} = 50\text{ V}$ , starting  $T_J = 25\text{ }^{\circ}\text{C}$ ,  $L = 4.6\text{ mH}$ ,  $R_g = 25\text{ }\Omega$ ,  $I_{AS} = 9.0\text{ A}$  (see fig. 12).
- $I_{SD} \leq 9.0\text{ A}$ ,  $dl/dt \leq 120\text{ A}/\mu\text{s}$ ,  $V_{DD} \leq V_{DS}$ ,  $T_J \leq 150\text{ }^{\circ}\text{C}$ .
- 1.6 mm from case.
- When mounted on 1" square PCB (FR-4 or G-10 material).

| THERMAL RESISTANCE RATINGS                           |            |      |      |      |                             |
|------------------------------------------------------|------------|------|------|------|-----------------------------|
| PARAMETER                                            | SYMBOL     | MIN. | TYP. | MAX. | UNIT                        |
| Maximum Junction-to-Ambient (PCB Mount) <sup>c</sup> | $R_{thJA}$ | -    | -    | 40   | $^{\circ}\text{C}/\text{W}$ |
| Maximum Junction-to-Ambient                          | $R_{thJA}$ | -    | -    | 62   |                             |
| Maximum Junction-to-Case (Drain)                     | $R_{thJC}$ | -    | -    | 1.7  |                             |

| SPECIFICATIONS (T <sub>J</sub> = 25 °C, unless otherwise noted) |                                  |                                                                                                                             |                                                                                   |      |      |           |
|-----------------------------------------------------------------|----------------------------------|-----------------------------------------------------------------------------------------------------------------------------|-----------------------------------------------------------------------------------|------|------|-----------|
| PARAMETER                                                       | SYMBOL                           | TEST CONDITIONS                                                                                                             |                                                                                   | MIN. | TYP. | MAX. UNIT |
| Static                                                          |                                  |                                                                                                                             |                                                                                   |      |      |           |
| Drain-Source Breakdown Voltage                                  | V <sub>DS</sub>                  | V <sub>GS</sub> = 0, I <sub>D</sub> = 250 μA                                                                                |                                                                                   | 200  | -    | - V       |
| V <sub>DS</sub> Temperature Coefficient                         | ΔV <sub>DS</sub> /T <sub>J</sub> | Reference to 25 °C, I <sub>D</sub> = 1 mA                                                                                   |                                                                                   | -    | 0.24 | - V/°C    |
| Gate-Source Threshold Voltage                                   | V <sub>GS(th)</sub>              | V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250 μA                                                                 |                                                                                   | 2.0  | -    | 4.0 V     |
| Gate-Source Leakage                                             | I <sub>GSS</sub>                 | V <sub>GS</sub> = ± 20 V                                                                                                    |                                                                                   | -    | -    | ± 100 nA  |
| Zero Gate Voltage Drain Current                                 | I <sub>DSS</sub>                 | V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V                                                                              |                                                                                   | -    | -    | 25 μA     |
|                                                                 |                                  | V <sub>DS</sub> = 160V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C                                                      |                                                                                   | -    | -    | 250       |
| Drain-Source On-State Resistance                                | R <sub>DS(on)</sub>              | V <sub>GS</sub> = 10 V                                                                                                      | I <sub>D</sub> = 5.4 A <sup>b</sup>                                               | -    | -    | 0.40 Ω    |
| Forward Transconductance                                        | g <sub>fs</sub>                  | V <sub>DS</sub> = 50 V, I <sub>D</sub> = 5.4 A <sup>b</sup>                                                                 |                                                                                   | 3.8  | -    | - S       |
| Dynamic                                                         |                                  |                                                                                                                             |                                                                                   |      |      |           |
| Input Capacitance                                               | C <sub>iss</sub>                 | V <sub>GS</sub> = 0 V,<br>V <sub>DS</sub> = 25 V,<br>f = 1.0 MHz, see fig. 5                                                |                                                                                   | -    | 800  | - pF      |
| Output Capacitance                                              | C <sub>oss</sub>                 |                                                                                                                             |                                                                                   | -    | 240  | -         |
| Reverse Transfer Capacitance                                    | C <sub>rss</sub>                 |                                                                                                                             |                                                                                   | -    | 76   | -         |
| Total Gate Charge                                               | Q <sub>g</sub>                   | V <sub>GS</sub> = 10 V                                                                                                      | I <sub>D</sub> = 5.9 A, V <sub>DS</sub> = 160 V<br>see fig. 6 and 13 <sup>b</sup> | -    | -    | 43 nC     |
| Gate-Source Charge                                              | Q <sub>gs</sub>                  |                                                                                                                             |                                                                                   | -    | -    | 7.0       |
| Gate-Drain Charge                                               | Q <sub>gd</sub>                  |                                                                                                                             |                                                                                   | -    | -    | 23        |
| Turn-On Delay Time                                              | t <sub>d(on)</sub>               | V <sub>DD</sub> = 100 V, I <sub>D</sub> = 5.9 A<br>R <sub>g</sub> = 12 Ω, R <sub>D</sub> = 16 Ω<br>see fig. 10 <sup>b</sup> |                                                                                   | -    | 9.4  | - ns      |
| Rise Time                                                       | t <sub>r</sub>                   |                                                                                                                             |                                                                                   | -    | 28   | -         |
| Turn-Off Delay Time                                             | t <sub>d(off)</sub>              |                                                                                                                             |                                                                                   | -    | 39   | -         |
| Fall Time                                                       | t <sub>f</sub>                   |                                                                                                                             |                                                                                   | -    | 20   | -         |
| Internal Drain Inductance                                       | L <sub>D</sub>                   | Between lead,<br>6 mm (0.25") from<br>package and center of<br>die contact                                                  |                                                                                   | -    | 4.5  | - nH      |
| Internal Source Inductance                                      | L <sub>S</sub>                   |                                                                                                                             |                                                                                   | -    | 7.5  | -         |



| SPECIFICATIONS ( $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted) |          |                                                                                                                                                     |      |      |      |               |
|-------------------------------------------------------------------------------|----------|-----------------------------------------------------------------------------------------------------------------------------------------------------|------|------|------|---------------|
| PARAMETER                                                                     | SYMBOL   | TEST CONDITIONS                                                                                                                                     | MIN. | TYP. | MAX. | UNIT          |
| Drain-Source Body Diode Characteristics                                       |          |                                                                                                                                                     |      |      |      |               |
| Continuous Source-Drain Diode Current                                         | $I_S$    | MOSFET symbol showing the integral reverse p - n junction diode  | -    | -    | 9.0  | A             |
| Pulsed Diode Forward Current <sup>a</sup>                                     | $I_{SM}$ |                                                                                                                                                     | -    | -    | 36   |               |
| Body Diode Voltage                                                            | $V_{SD}$ | $T_J = 25\text{ }^{\circ}\text{C}$ , $I_S = 9.0\text{ A}$ , $V_{GS} = 0\text{ V}^b$                                                                 | -    | -    | 2.0  | V             |
| Body Diode Reverse Recovery Time                                              | $t_{rr}$ | $T_J = 25\text{ }^{\circ}\text{C}$ , $I_F = 5.9\text{ A}$ , $dI/dt = 100\text{ A}/\mu\text{s}^b$                                                    | -    | 170  | 340  | ns            |
| Body Diode Reverse Recovery Charge                                            | $Q_{rr}$ |                                                                                                                                                     | -    | 1.1  | 2.2  | $\mu\text{C}$ |
| Forward Turn-On Time                                                          | $t_{on}$ | Intrinsic turn-on time is negligible (turn-on is dominated by $L_S$ and $L_D$ )                                                                     |      |      |      |               |

## Notes

- Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
- Pulse width  $\leq 300\text{ }\mu\text{s}$ ; duty cycle  $\leq 2\%$ .
- When mounted on 1" square PCB (FR-4 or G-10 material).

## TYPICAL CHARACTERISTICS ( $25\text{ }^{\circ}\text{C}$ , unless otherwise noted)

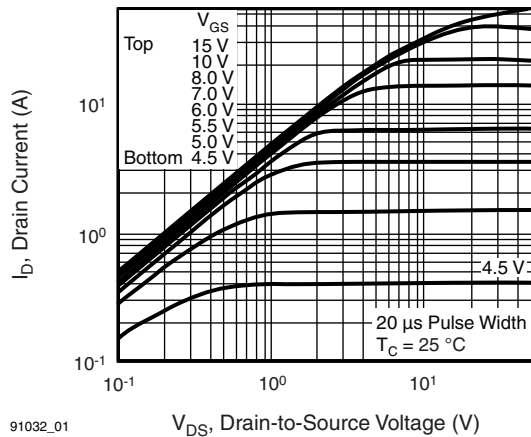


Fig. 1 - Typical Output Characteristics,  $T_C = 25\text{ }^{\circ}\text{C}$

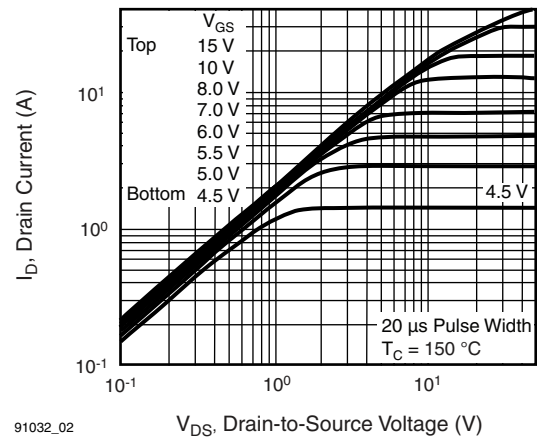
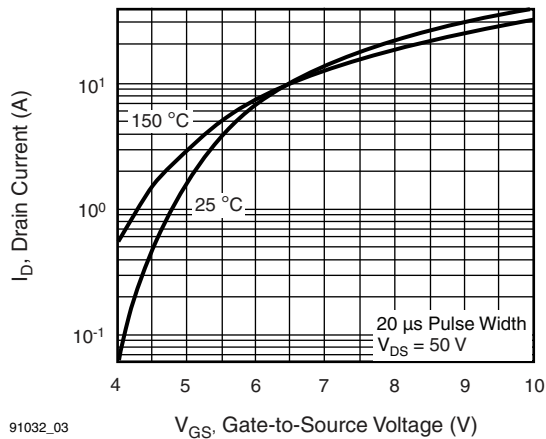
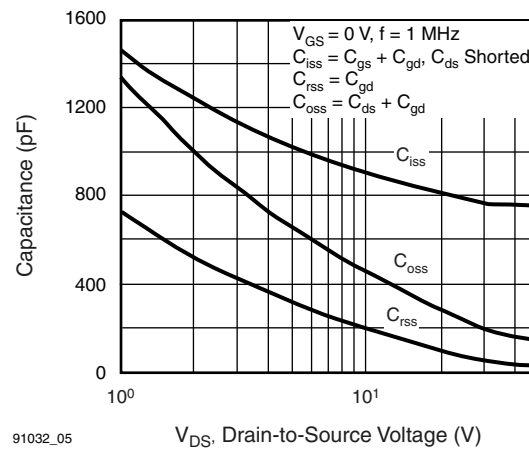


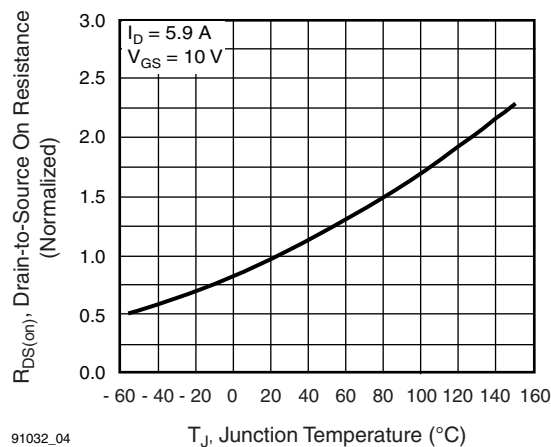
Fig. 2 - Typical Output Characteristics,  $T_C = 150\text{ }^{\circ}\text{C}$



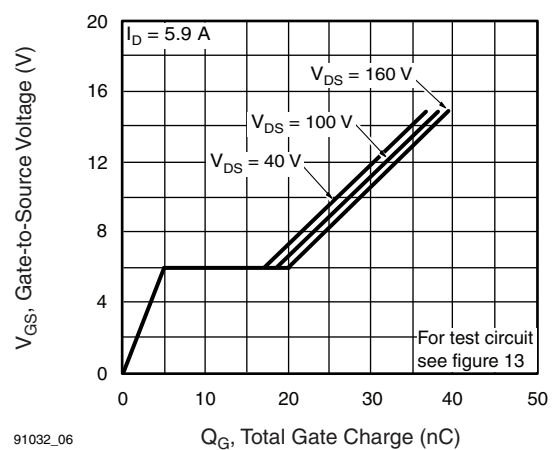
**Fig. 3 - Typical Transfer Characteristics**



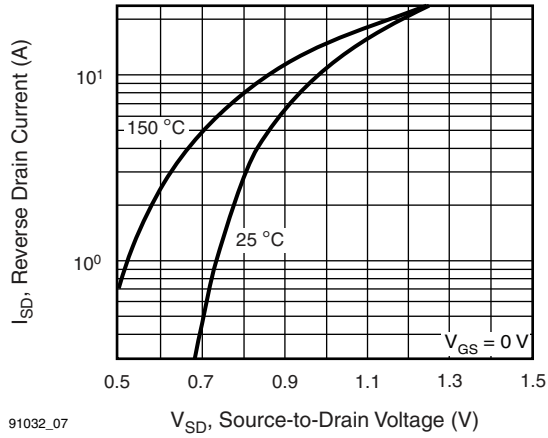
**Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage**



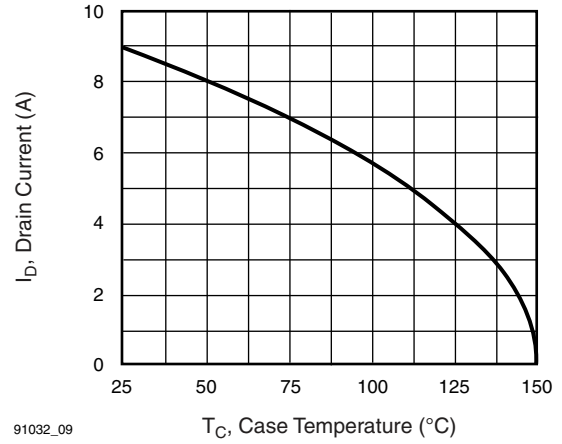
**Fig. 4 - Normalized On-Resistance vs. Temperature**



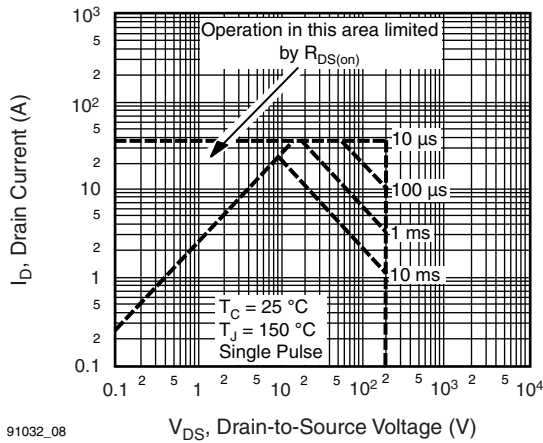
**Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage**



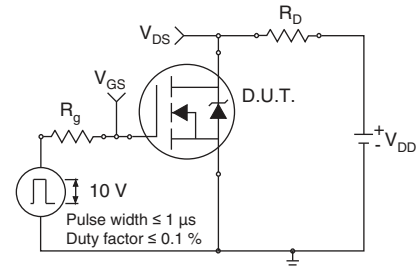
**Fig. 7 - Typical Source-Drain Diode Forward Voltage**



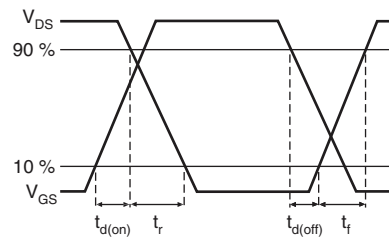
**Fig. 9 - Maximum Drain Current vs. Case Temperature**



**Fig. 8 - Maximum Safe Operating Area**



**Fig. 10a - Switching Time Test Circuit**



**Fig. 10b - Switching Time Waveforms**

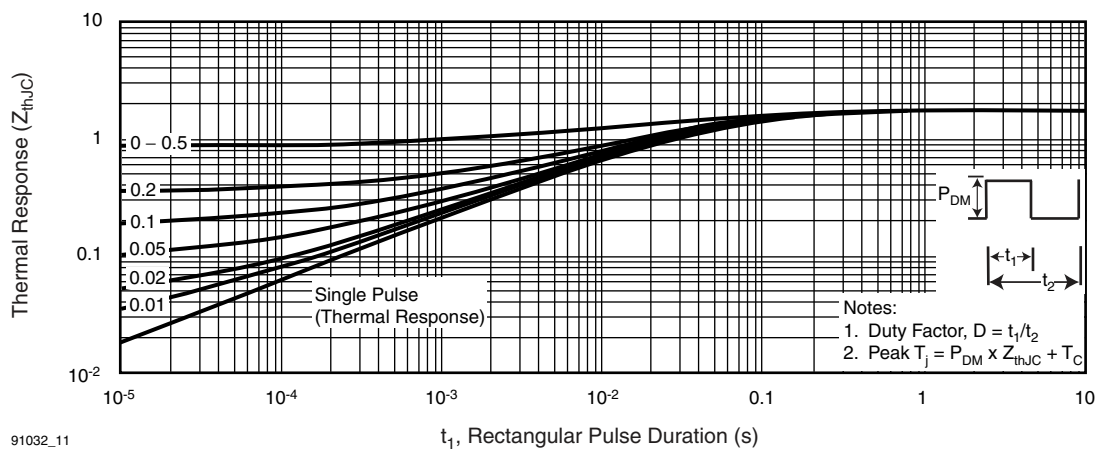


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

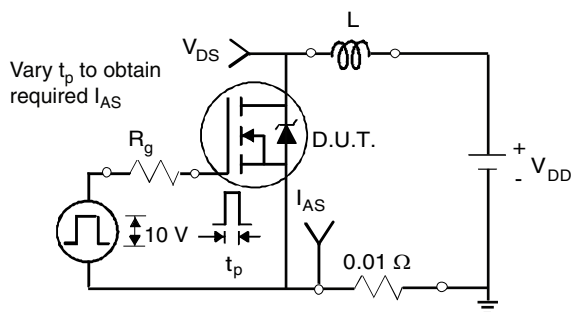


Fig. 12a - Unclamped Inductive Test Circuit

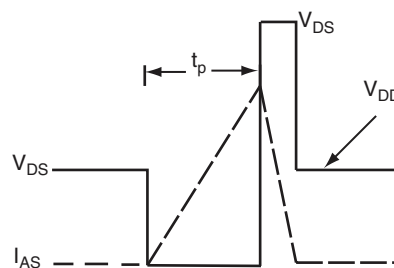


Fig. 12b - Unclamped Inductive Waveforms

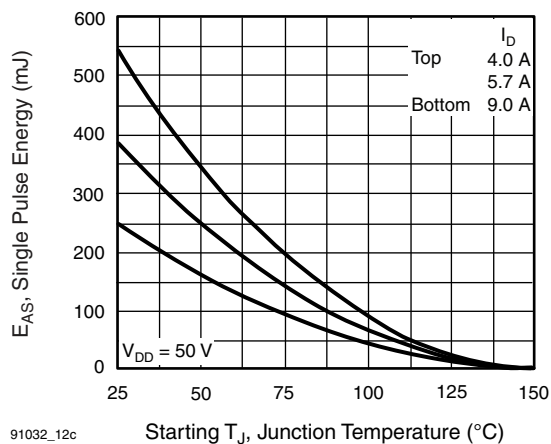


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

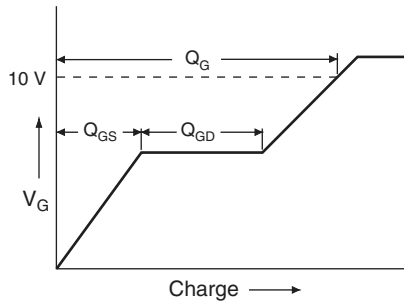


Fig. 13a - Basic Gate Charge Waveform

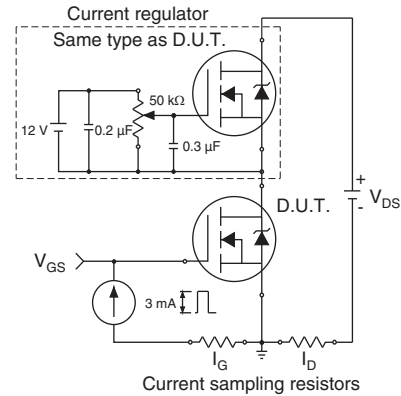


Fig. 13b - Gate Charge Test Circuit

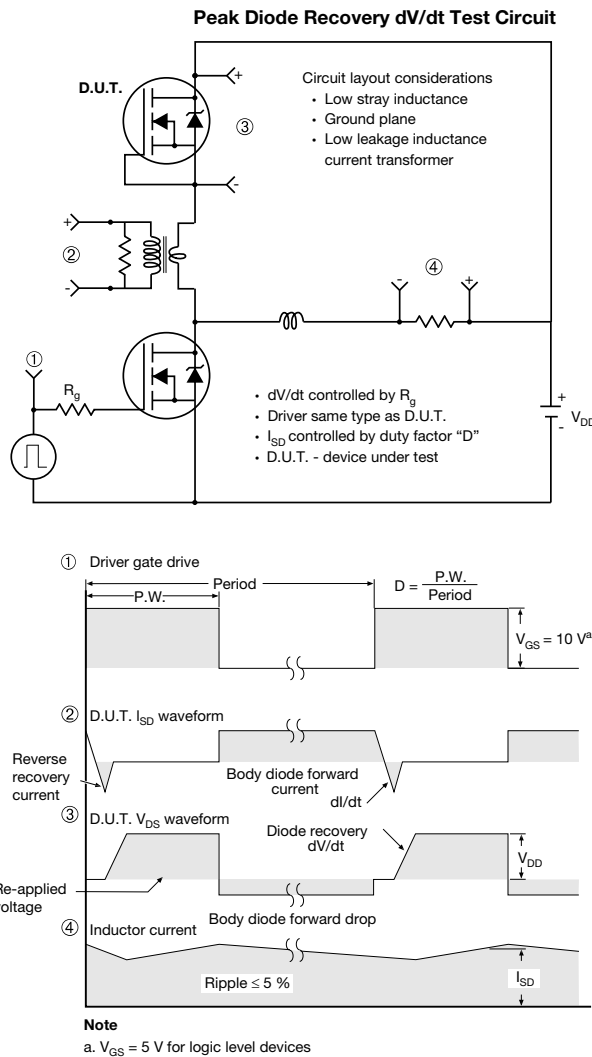


Fig. 14 - For N-Channel

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see [www.vishay.com/ppg?91032](http://www.vishay.com/ppg?91032).

## TO-263AB (HIGH VOLTAGE)



| DIM. | MILLIMETERS |      | INCHES |       |
|------|-------------|------|--------|-------|
|      | MIN.        | MAX. | MIN.   | MAX.  |
| A    | 4.06        | 4.83 | 0.160  | 0.190 |
| A1   | 0.00        | 0.25 | 0.000  | 0.010 |
| b    | 0.51        | 0.99 | 0.020  | 0.039 |
| b1   | 0.51        | 0.89 | 0.020  | 0.035 |
| b2   | 1.14        | 1.78 | 0.045  | 0.070 |
| b3   | 1.14        | 1.73 | 0.045  | 0.068 |
| c    | 0.38        | 0.74 | 0.015  | 0.029 |
| c1   | 0.38        | 0.58 | 0.015  | 0.023 |
| c2   | 1.14        | 1.65 | 0.045  | 0.065 |
| D    | 8.38        | 9.65 | 0.330  | 0.380 |

| DIM. | MILLIMETERS |       | INCHES    |       |
|------|-------------|-------|-----------|-------|
|      | MIN.        | MAX.  | MIN.      | MAX.  |
| D1   | 6.86        | -     | 0.270     | -     |
| E    | 9.65        | 10.67 | 0.380     | 0.420 |
| E1   | 6.22        | -     | 0.245     | -     |
| e    | 2.54 BSC    |       | 0.100 BSC |       |
| H    | 14.61       | 15.88 | 0.575     | 0.625 |
| L    | 1.78        | 2.79  | 0.070     | 0.110 |
| L1   | -           | 1.65  | -         | 0.066 |
| L2   | -           | 1.78  | -         | 0.070 |
| L3   | 0.25 BSC    |       | 0.010 BSC |       |
| L4   | 4.78        | 5.28  | 0.188     | 0.208 |

ECN: S-82110-Rev. A, 15-Sep-08  
DWG: 5970

### Notes

1. Dimensioning and tolerancing per ASME Y14.5M-1994.
2. Dimensions are shown in millimeters (inches).
3. Dimension D and E do not include mold flash. Mold flash shall not exceed 0.127 mm (0.005") per side. These dimensions are measured at the outmost extremes of the plastic body at datum A.
4. Thermal PAD contour optional within dimension E, L1, D1 and E1.
5. Dimension b1 and c1 apply to base metal only.
6. Datum A and B to be determined at datum plane H.
7. Outline conforms to JEDEC outline to TO-263AB.



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**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**